

IRFU9110PBF-VB Datasheet P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)			
- 100	0.215 at $V_{GS} = -10 \text{ V}$	- 12	11			
	0.234 at $V_{GS} = -4.5 \text{ V}$	- 10] ''			

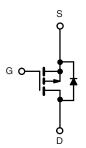
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g and UIS Tested Compliant to RoHS Directive 2002/95/EC





- · Power Switch
- DC/DC Converters



P-Channel MOSFET

	TO-251					
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ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted					
Parameter			Limit	Unit	
Drain-Source Voltage			- 100	V	
Gate-Source Voltage			± 20	V	
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 25 °C	I-	- 12	A	
Continuous Diain Current (1) = 150 C)	T _C = 70 °C	- I _D	- 8		
Pulsed Drain Current	I _{DM}	- 30	A		
Avalanche Current	I _{AS}	- 20			
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	16.2	mJ	
	T _C = 25 °C	Б	32.1 ^b	147	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	- P _D	2.5	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	50	°C/W		
Junction-to-Case (Drain)	R _{thJC}	3.9	C/VV		

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		·		•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 100			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 2.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V _{DS} = - 100 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 125 °C			- 50) μΑ	
		V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 150 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 15			Α	
	_	V _{GS} = - 10 V, I _D = - 3.6 A		0.215		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 3.4 A		0.234			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 3.6 A		12		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1055		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 50 V, f = 1 MHz		65			
Reverse Transfer Capacitance	C _{rss}	1		41			
	Qg	V _{DS} = -50 V, V _{GS} = -10 V, I _D = -3.6 A		23			
Total Gate Charge ^c				11		nC	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = -50 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -3.6 \text{ A}$		3.5			
Gate-Drain Charge ^c	Q_{gd}]		4.8			
Gate Resistance	R_g	f = 1 MHz	1.2	5.7	11.5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			7	14		
Rise Time ^c	t _r	$V_{DD} = -50 \text{ V}, R_L = 17.2 \Omega$		12	18		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 2.9 A, V_{GEN} = - 10 V, R_g = 1 Ω		33	50	ns	
Fall Time ^c	t _f	1		9	18		
Drain-Source Body Diode Ratings ar	nd Characteri	stics T _C = 25 °C ^b		•			
Continuous Current	I _S				- 8.8		
Pulsed Current	I _{SM}	М			- 15	A	
Forward Voltage ^a	V _{SD}	I _F = - 2.9 A, V _{GS} = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}			50	75	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 2.9 A, dl/dt = 100 A/μs		- 4	- 6	Α	
Reverse Recovery Charge	Q _{rr}	†		98	147	nC	

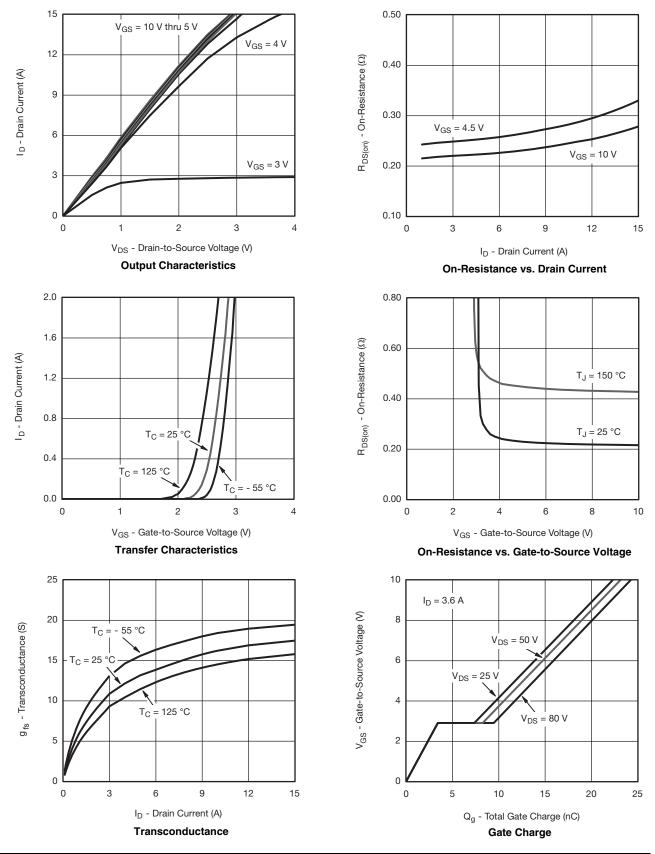
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

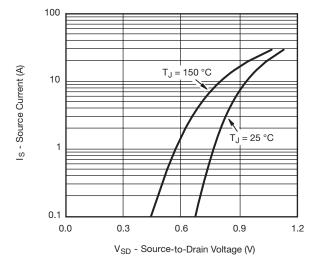


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

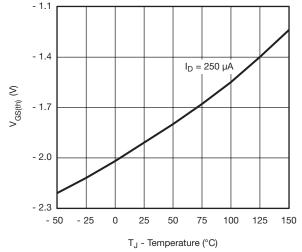




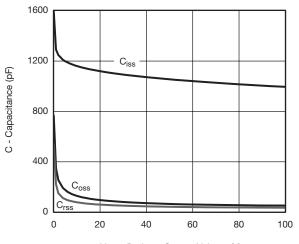
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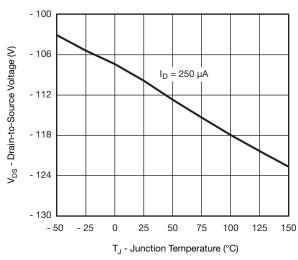
Source-Drain Diode Forward Voltage



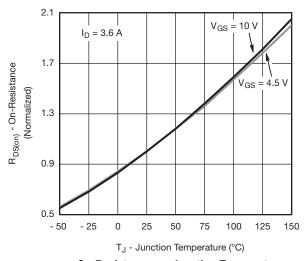
Threshold Voltage



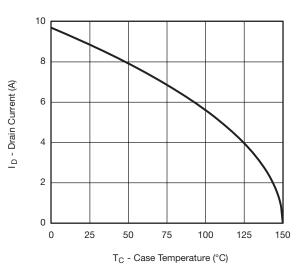
 V_{DS} - Drain-to-Source Voltage (V) $\label{eq:capacitance}$



Drain Source Breakdown vs. Junction Temperature



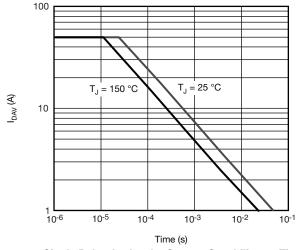
On-Resistance vs. Junction Temperature

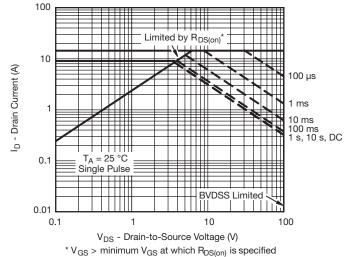


Current Derating



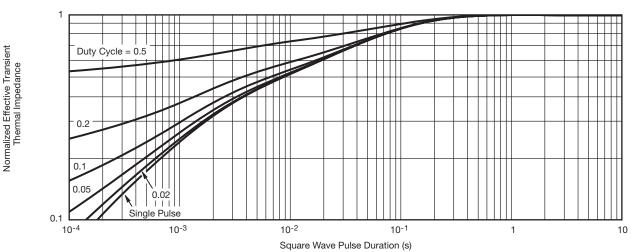
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Single Pulse Avalanche Current Capability vs. Time

Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

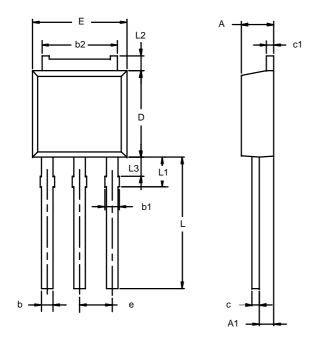
服务热线:400-655-8788

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TO-251AA (DPAK)

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Note:	Dimension	1.3 is 1	for re	ference	only
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	MILLIM	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					



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